

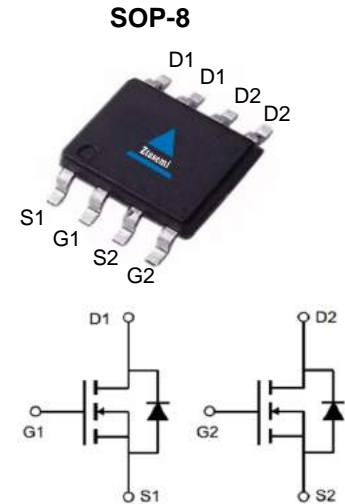
Features

- Dual N-Channel
- Advanced Trench Technology
- Excellent $R_{DS(on)}$ and Low Gate Charge
- Lead Free
- 100% EAS Tested

| | | |
|-------------------------------|-----|------------|
| V_{DS} | 20 | V |
| $R_{DS(on),TYP@ V_{GS}=4.5V}$ | 14 | m Ω |
| $R_{DS(on),TYP@ V_{GS}=2.5V}$ | 18 | m Ω |
| I_D | 6.5 | A |



| Part ID | Package Type | Marking | Packing |
|---------|--------------|---------|--------------|
| ZT9926 | SOP-8 | 9926 | 4000pcs/reel |



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

| Symbol | Parameter | Rating | Unit | |
|--|---|--------------------------------|--------------------|---|
| Common Ratings ($T_c=25^\circ\text{C}$ Unless Otherwise Noted) | | | | |
| V_{GS} | Gate-Source Voltage | ± 12 | V | |
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage | 20 | V | |
| T_J | Maximum Junction Temperature | 150 | $^\circ\text{C}$ | |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ\text{C}$ | |
| I_{DM} | Drain Current-Continuous@ Current-Pulsed (Note 1) | $T_c = 25^\circ\text{C}$ 26 | A | |
| Mounted on Large Heat Sink | | | | |
| I_D | Drain Current-Continuous | $T_c = 25^\circ\text{C}$ | 6.5 | A |
| | | $T_c = 100^\circ\text{C}$ | 4 | A |
| P_D | Maximum Power Dissipation | 1.6 | W | |
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient | 76 | $^\circ\text{C/W}$ | |
| Drain-Source Avalanche Ratings | | | | |
| EAS | Avalanche Energy, Single Pulsed (Note 2) | 25 | mJ | |

Electrical Characteristics (T_J=25°C unless otherwise noted)

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|----------------------------------|--|-----|------|------|------|
| Static Electrical Characteristics @ T_J=25°C (unless otherwise stated) | | | | | | |
| V(BR)DSS | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 20 | -- | -- | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =20V, V _{GS} =0V | -- | -- | 1 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{GS} =±12V, V _{DS} =0V | -- | -- | ±100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 0.5 | 0.7 | 1.0 | V |
| R _{DS(on)} | Drain-Source On-State Resistance | V _{GS} =4.5V, I _D =6.5A | -- | 14 | 18 | mΩ |
| R _{DS(on)} | Drain-Source On-State Resistance | V _{GS} =2.5V, I _D =5A | -- | 18 | 23 | mΩ |
| Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated) | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} =10V, V _{GS} =0V, f=1MHz | -- | 649 | -- | pF |
| C _{oss} | Output Capacitance | | -- | 120 | -- | pF |
| C _{rss} | Reverse Transfer Capacitance | | -- | 106 | -- | pF |
| Q _g | Total Gate Charge | V _{DD} =10V, I _D =3.5A, V _{GS} =4.5V | -- | 8.8 | -- | nC |
| Q _{gs} | Gate-Source Charge | | -- | 1.1 | -- | nC |
| Q _{gd} | Gate-Drain Charge | | -- | 2.4 | -- | nC |
| Switching Characteristics | | | | | | |
| T _{d(on)} | Turn-on Delay Time | V _{DD} =10V, I _D =3.5A, R _G =3.0Ω, V _{GS} =4.5V | -- | 10.6 | -- | ns |
| T _r | Turn-on Rise Time | | -- | 30.1 | -- | ns |
| T _{d(off)} | Turn-Off Delay Time | | -- | 30.2 | -- | ns |
| T _f | Turn-Off Fall Time | | -- | 34.8 | -- | ns |
| Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated) | | | | | | |
| I _S | Diode Forward Current | | -- | -- | 6.5 | A |
| V _{SD} | Forward on voltage | I _S =6.5A, V _{GS} =0V | -- | -- | 1.2 | V |
| T _{rr} | Reverse Recovery Time | I _F =6A, | -- | 8.5 | -- | ns |
| Q _{rr} | Reverse Recovery Charge | di/dt=100A/μs | -- | 2 | -- | nC |

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition : Starting T_J=25°C, V_{DD}=10V, V_G=10V, L=0.5mH, R_G=25Ω, I_{AS}=10A
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

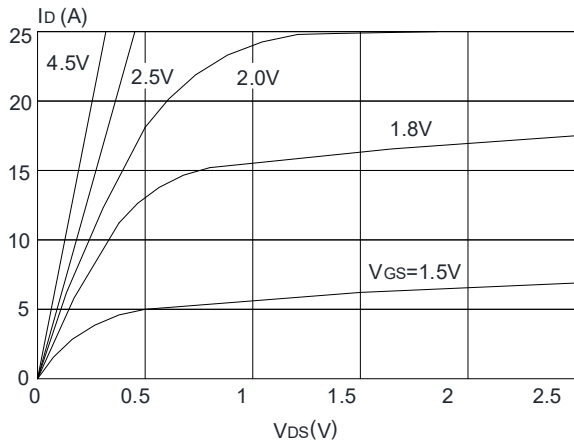


Figure 1: Output Characteristics

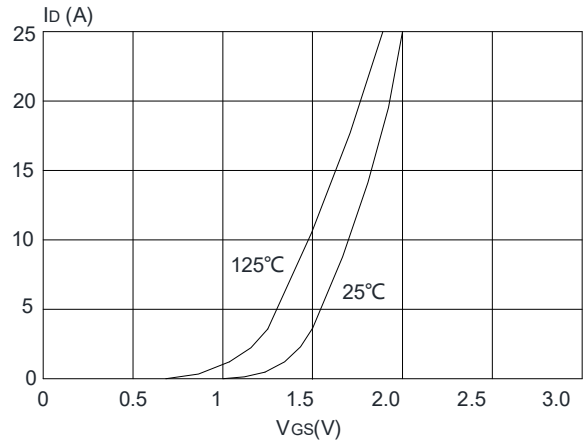


Figure 4: Typical Transfer Characteristics

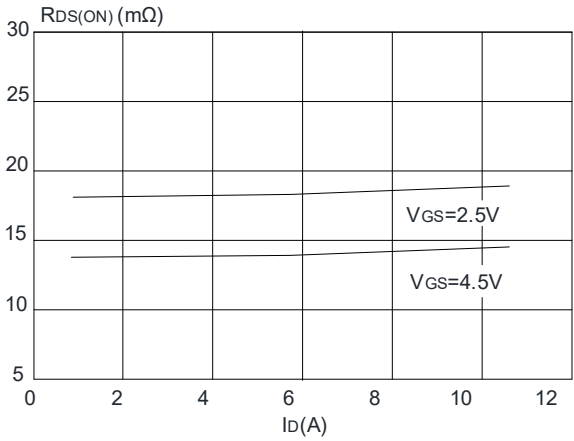


Figure 2: On-resistance vs. Drain Current

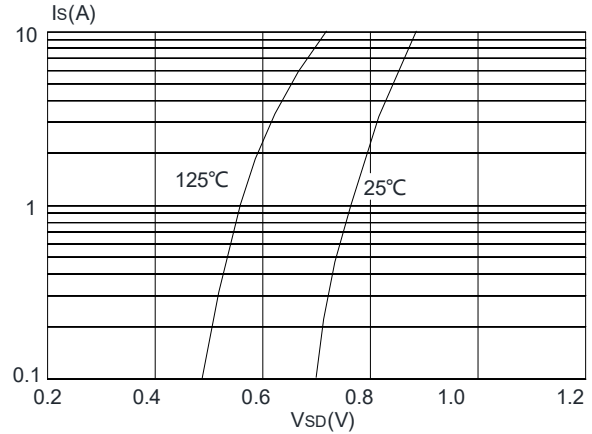


Figure 5: Body Diode Characteristics

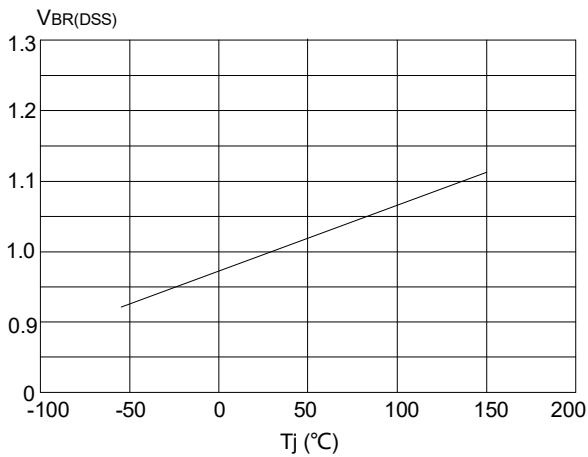


Figure 3: Normalized Breakdown Voltage vs. Junction Temperature

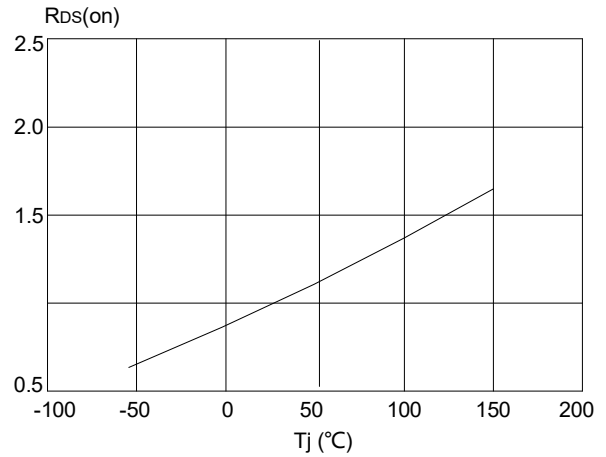


Figure 6: Normalized on Resistance vs. Junction Temperature

Typical Performance Characteristics

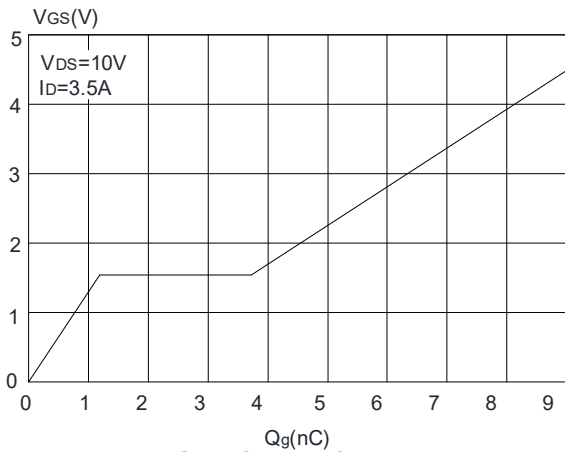


Figure 7: Gate Charge Characteristics

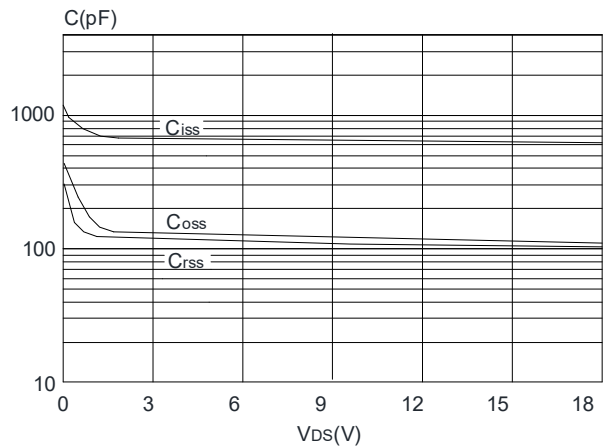


Figure 9: Capacitance Characteristics

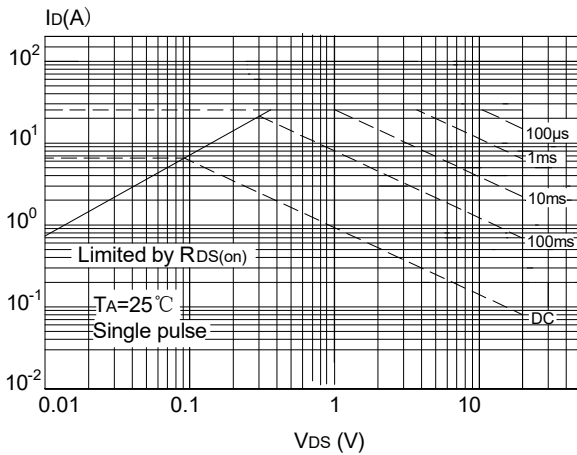


Figure 8: Maximum Safe Operating Area

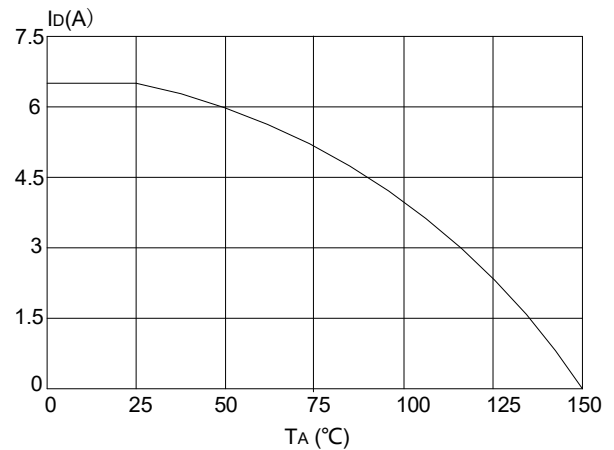


Figure 10: Maximum Continuous Drain Current vs Ambient Temperature

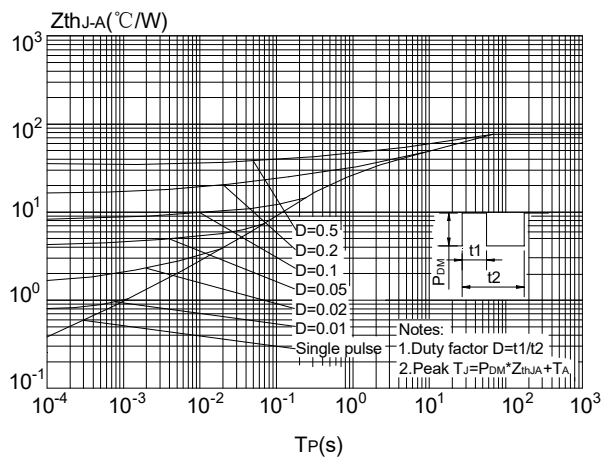


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

Test Circuit

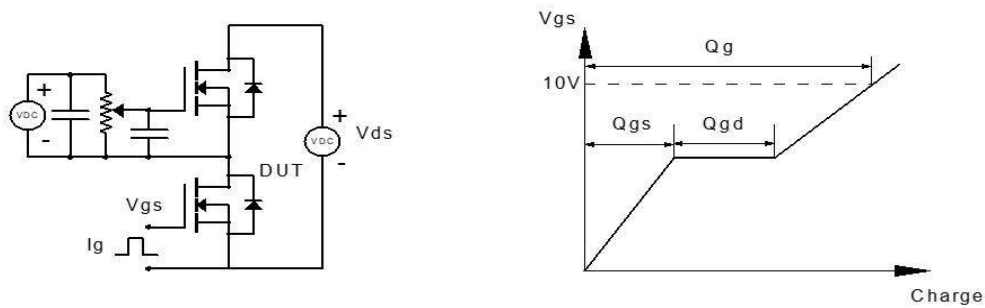


Figure 1: Gate Charge Test Circuit & Waveform

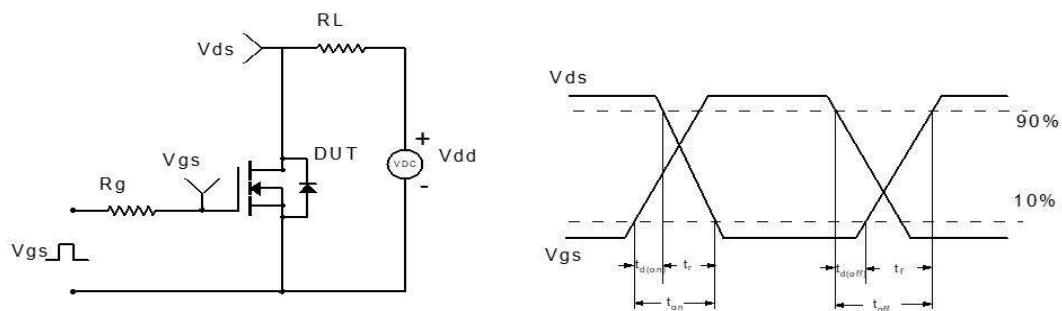


Figure 2: Resistive Switching Test Circuit & Waveform

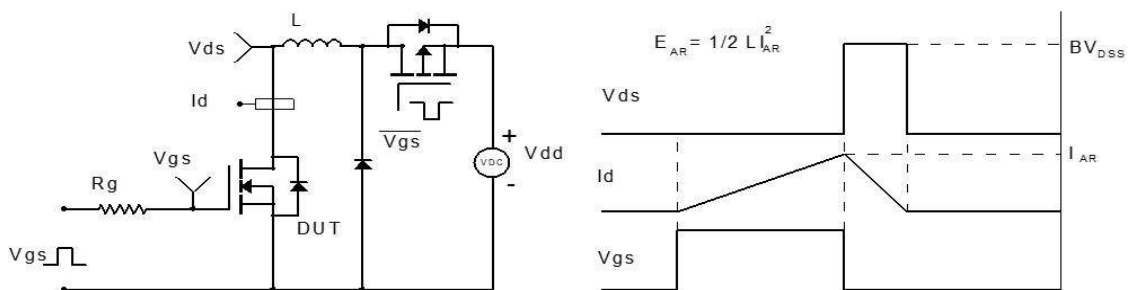


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

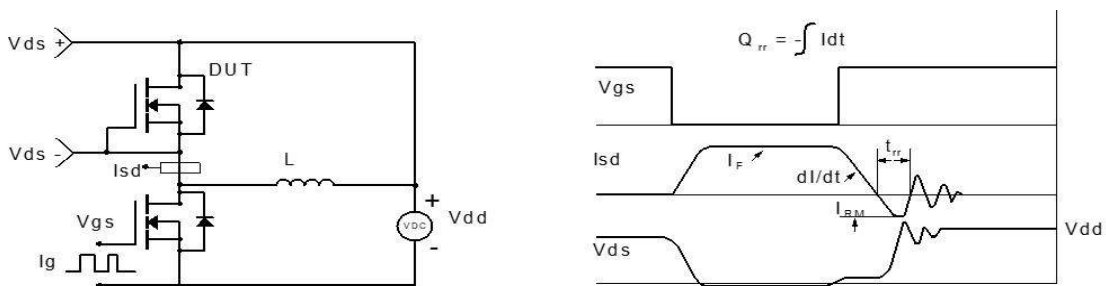
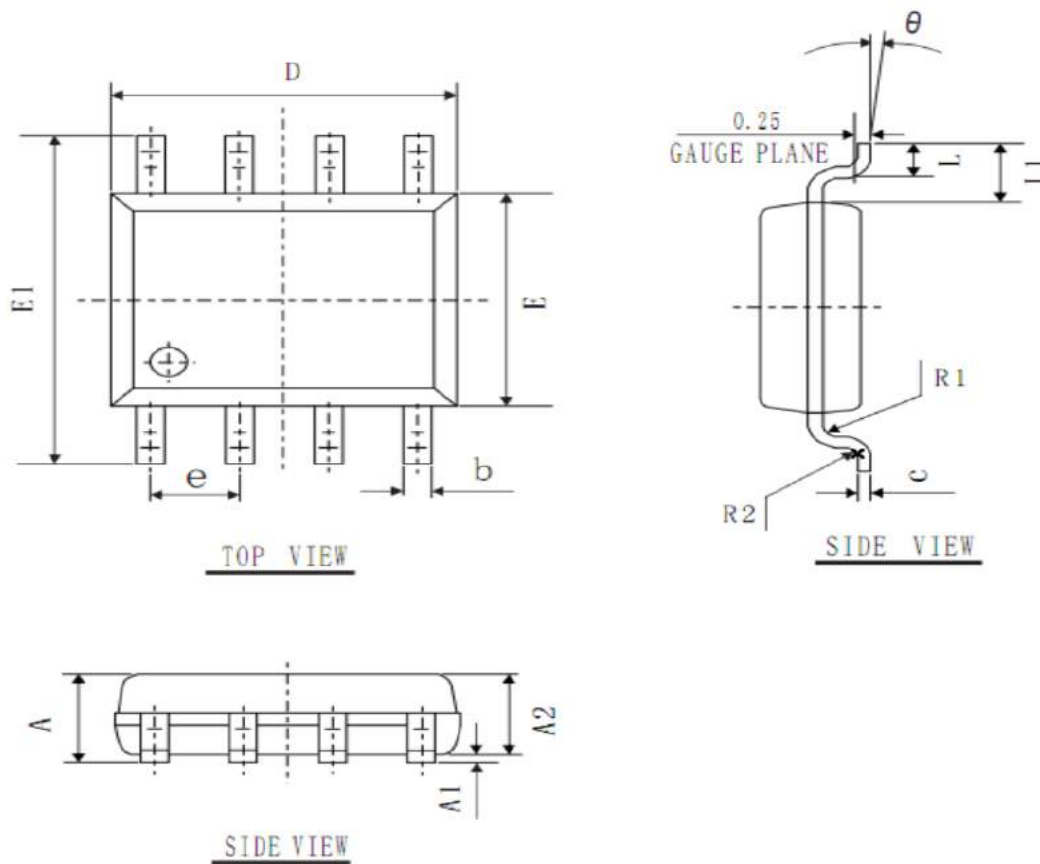


Figure 4: Diode Recovery Test Circuit & Waveform

SOP-8 Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

| SYMBOL | MIN | NOM | MAX |
|----------|----------|-------|-------|
| A | 1.40 | 1.60 | 1.80 |
| A1 | 0.05 | 0.15 | 0.25 |
| A2 | 1.35 | 1.45 | 1.55 |
| b | 0.30 | 0.40 | 0.50 |
| c | 0.153 | 0.203 | 0.253 |
| D | 4.80 | 4.90 | 5.00 |
| E | 3.80 | 3.90 | 4.00 |
| E1 | 5.80 | 6.00 | 6.20 |
| L | 0.45 | 0.70 | 1.00 |
| θ | 2° | 4° | 6° |
| L1 | 1.04 REF | | |
| e | 1.27 BSC | | |
| R1 | 0.07 TYP | | |
| R2 | 0.07 TYP | | |

Customer Service

Sales and Service:

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